

■ Typical Specifications

Items	Specifications
Rating (max.)/(min.) (Resistive load)	1mA 5V DC / 50μA 3V DC
Contact resistance (Initial / After operating life)	200mΩ max. / 250mΩ max.
Rotational torque	13±5mN·m
Operating life with load	10,000 cycles (1mA 5V DC)
Voltage proof	100V AC 1minute

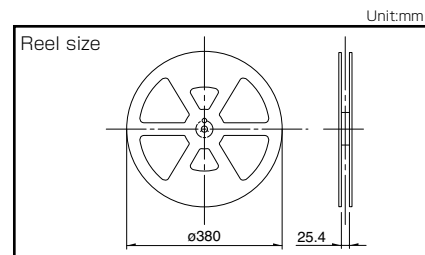
■ Product Line

Poles	Positions	Changeover angle	Detent	Location lug	Changeover timing	Soldering	Actuator length (mm)	Minimum order unit (pcs.)		Product No.	Drawing No.
								Japan	Export		
1	10	36°	5	with	Non shorting	For PC board (Reflow)	1.7	1,200	4,800	SRBD150201	1
			7	without						SRBD170401	2
			8	with						SRBD180201	1
			10							SRBD110401	

■ Packing Specifications

Taping

Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
1 reel	1 case /Japan	1 case /export packing		
1,200	2,400	4,800	24	428×413×172



Detector
Slide
Push
Rotary
Power
Dual-In-line Package Type

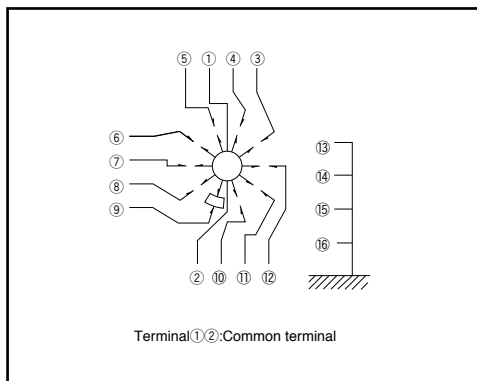
SRBD Heavy-torque Feel, Low-profile Type

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from direction A)
1		
2		

Circuit Diagram (Viewed from Direction A)

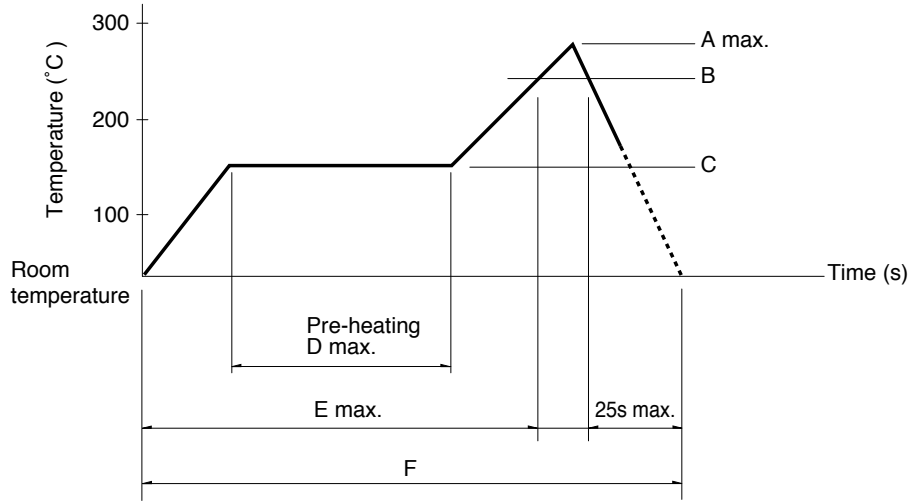


Correspondence Table of Terminal No. and Detent

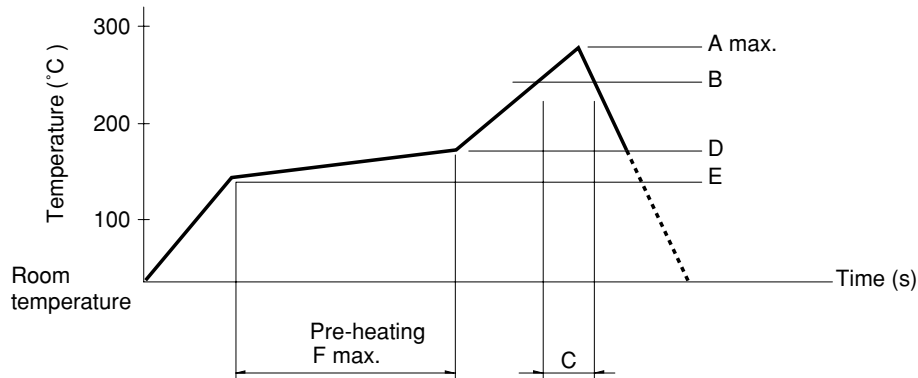
Position No.	Terminal No.	Detent			
		5	7	8	10
1	③	—	○	—	○
2	④	—	○	○	○
3	⑤	—	○	○	○
4	⑥	○	○	○	○
5	⑦	○	○	○	○
6	⑧	○	○	○	○
7	⑨	○	○	○	○
8	⑩	○	—	○	○
9	⑪	—	—	○	○
10	⑫	—	—	—	○

Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple $\phi 0.1$ to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)	A (°C) 3s max.	B (°C)	C (°C)	D (s)	E (s)	F (s)
SRBQ	250	200	150±5	80 to 100	—	—



Series (Reflow type)	A (°C) 3s max.	B (°C)	C (s)	D (°C)	E (°C)	F (s)
SRBD	260	230	40	180	150	120

- Notes**
1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SRBQ, SRBM, SRBV, SRRM, SRRN	350±10°C	3+1/0s
SRBQ (Reflow type)	350±5°C	3s max.

Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SRBM	100°C max.	60s max.	260±5°C	5s max.
SRBV, SRRM, SRRN	—	—	260±5°C	10±1s
SRBQ	—	—	260±5°C	5±1s